

SPECIFICATION FOR LCD MODULE MODULE NO: YB-TG480800S13A-C-A0 Doc.Version:00

Customer Approval:

□ Accept

Reject

| YEEBO | NAME | SIGNATURE | DATE |
|----------|---------------------|-----------|-----------|
| Prepare | Electronic Engineer | 袁江秘 | 2019/5/11 |
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| | · | | • |

□ APPROVAL FOR SPECIFICATIONS ONLY ■ APPROVAL FOR SPECIFICATIONS AND SAMPLE

WIMRD005-02-C



<u>1. Revision History</u>

| Sample Version | DOC. Version | DATE | | CHANGED BY | |
|-------------------|-----------------|------------|-----------|--------------|------|
| A0 | 00 | 2019-05-08 | FULL SPEC | First Sample | Yuan |
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<u>2. Table of Contents:</u>

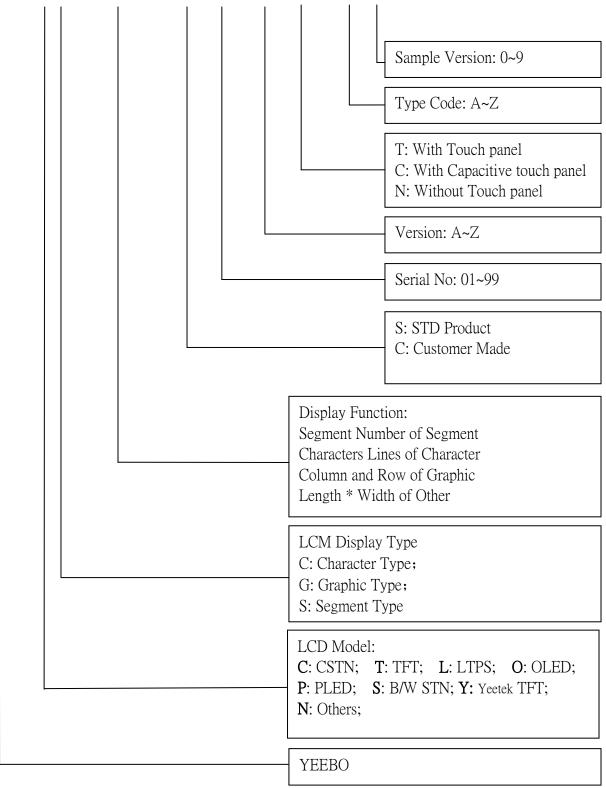
| NO | CONTENTS | PAGE | | | |
|----|----------------------------------------|------|--|--|--|
| 1 | Revision History | | | | |
| 2 | Table of Contents | 2 | | | |
| 3 | Module Numbering System | 3 | | | |
| 4 | General Specification | 4 | | | |
| 5 | LCM drawing | 5 | | | |
| 6 | Electrical Characteristics | 6 | | | |
| 7 | Optical Characteristics | 9 | | | |
| 8 | Interface Pin Assignment | 11 | | | |
| 9 | Block Diagram | 13 | | | |
| 10 | Backlight | 14 | | | |
| 11 | Standard Specification for Reliability | 15 | | | |
| 12 | Specification of Quality Assurance | 17 | | | |
| 13 | Handling Precaution | 25 | | | |
| 14 | Guarantee | 25 | | | |



3. Module Numbering System:

(Example)

<u>YB- TG 480800 S 13 A -C – A 0</u>



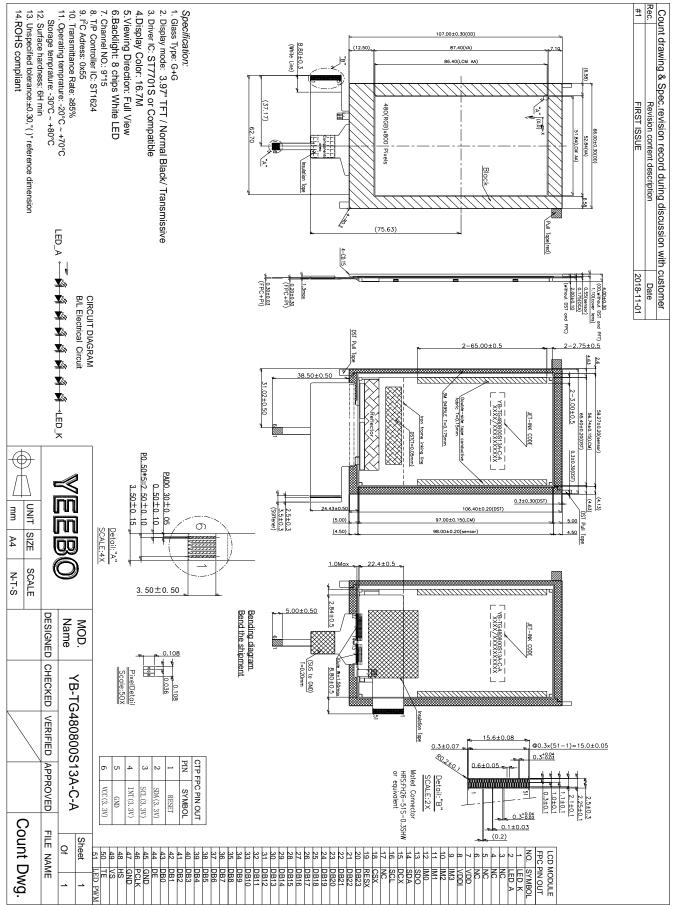


4. General Specification:

| ITEM | CONTENTS |
|------------------------|-------------------------------------------|
| Module Size | 66.00 (W) * 107.00 (H) * 4.0 (T) mm |
| Module Size(With FPC) | 70.17 (W) * 126.43 (H) * 4.0 (T) mm |
| Display Size(Diagonal) | 3.97inch |
| Display Format | 480(RGB) * 800 Pixels |
| Active Area | 52.84*87.40mm |
| Piexl Pitch | 0.108*0.108 mm |
| LCD Type | 16.7M Color / Transmissive / Normal Black |
| Viewing Direction | Free |
| Driver IC | ST7701S |
| CTP IC | ST1624 |
| CTP Interface | I2C |
| Weight(g) | ≈46.31g |
| Firmware | 8975_20181205.dumo |
| Test Configuration | FW5238_8975_ZH_20181205_093845.prj |



5. LCM drawing:



Module P/N: YB-TG480800S13A-C-A0 Doc.Version:00

6. Electrical Characteristics(TFT)

6-1 Absolute Maximum Ratings

| | <u> </u> | | | | | , |
|----------------------------|----------|------|------|-----------|------|--------|
| Item | Symbol | Min. | Туре | Max. | Unit | Remark |
| Power Supply Voltage | Vdd | -0.3 | - | 4.8 | V | |
| Supply Voltage(Logic) | Vddi | -0.3 | - | 4.6 | V | |
| Logic Input Voltage Range | Vih | -0.3 | - | VDDI +0.5 | V | |
| Logic Output Voltage Range | Vон | -0.3 | - | VDDI +0.5 | V | |
| Operating Temperature | Topr | -20 | - | +70 | °C | |
| Storage Temperature | Tstg | -30 | - | +80 | °C | |

Note : Even if the absolute maximum rating of one of the above parameters is exceeded only for a short while, the quality of the product may be degraded. Therefore, be sure to use the product within the range of the absolute maximum ratings.

6-2 Operating Conditions

(Ta=25°C)

| 1 8 | | | | | | × . | - / |
|-----------------------|--------|-----------|----------|------|----------|------|--------|
| Item | Symbol | Condition | Min. | Туре | Max. | Unit | Remark |
| Power Supply Voltage | Vdd | - | 2.5 | 2.8 | 3.6 | V | |
| Supply Voltage(Logic) | Vddi | - | 1.68 | 2.8 | 3.3 | V | |
| | Vih | - | 0.7 Vddi | - | Vddi | V | |
| IO Supply Voltage | Vil | - | Vss | - | 0.3 Vddi | V | |
| IO Supply Voltage | Vон | - | 0.8 Vddi | - | Vddi | mA | |
| | Vol | - | Vss | - | 0.2 Vddi | V | |
| Power Supply Current | Idd | VDD=2.8V | - | 46.6 | 69.9 | mA | |



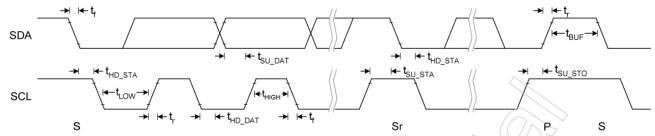
6-3 Power Supply (CTP)

- Operation voltage

 VDD = 2.7V ~ 3.6V
 IOVDD = 1.6V ~ 3.6V
- Operation Temperature: -20°C ~ 80°C
- Storage Temperature: -40°C ~ 125°C

6-4 DC Characteristics (Topr = 25° C)

The timing of I2C Interface



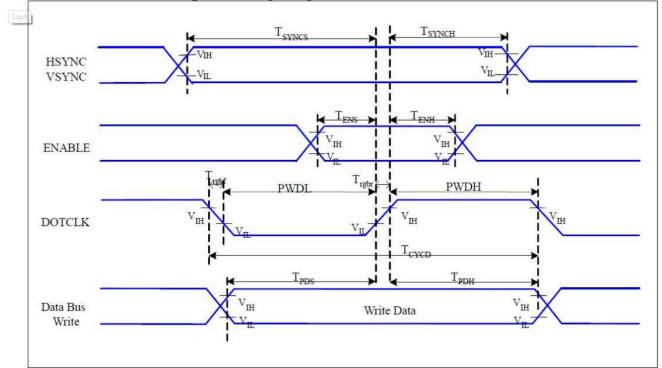
Characteristics of the SDA and SCL bus lines

| Symbol | Parameter | | Unit | | |
|-------------------------|---------------------------------------------------------------------------------------------------|------|--------|------|------|
| Symbol | i arameter | Min. | Тур. | Max. | onic |
| f _{SCL} | SCL clock frequency | 0 | \sum | 400 | kHz |
| t _{LOW} | Low period of the SCL clock | 1.3 | | - | us |
| t _{HIGH} | High period of the SCL clock | 0.6 |)/ - | - | us |
| t _f | Signal falling time | 7(| - | 300 | ns |
| t _r | Signal rising time | Ľ | - | 300 | ns |
| t _{su_sta} | Set up time for a repeated START condition | 0.6 | - | - | us |
| t _{hd_sta} | Hold time (repeated) START condition. After this period, the first clock pulse is generated | 0.6 | - | - | us |
| t _{su dat} | Data set up time | 100 | - | - | ns |
| t _{HD DAT} | Data hold time | 0 | - | 0.9 | us |
| t _{su sто} | Set up time for STOP condition | 0.6 | - | - | us |
| t _{BUF} | Bus free time between a STOP and START condition | 1.3 | - | - | us |
| Cb | Capacitive load for each bus line | - | - | 400 | pF |

Condit is: VDD = 3.3V, GND = 0V, $T_A = 25^{\circ}C$



6-5 Timing Characteristics(TFT) 6-5-1 Clock and data input timing diagram



6-5-2 RGB input timing table6-5-2-1 Parallel 24-bit RGB timing table

VDDI=1.8, VDD=2.8, AGND=DGND=0V, Ta=25 °C

| Signal | Symbol | Parameter | MIN | MAX | Unit | Description |
|--------|--------------------|-------------------------------|-----|-----|------|-------------|
| HSYNC, | т | VSYNC, HSYNC Setup Time | 5 | | 20 | |
| VSYNC | T _{SYNCS} | VSTNC, HSTNC Selup Time | 5 | - | ns | |
| ENABLE | T _{ENS} | Enable Setup Time | 5 | - | ns | |
| ENABLE | T _{ENH} | Enable Hold Time | 5 | - | ns | |
| | PWDH | DOTCLK High-level Pulse Width | 13 | - | ns | |
| DOTCLK | PWDL | DOTCLK Low-level Pulse Width | 13 | - | ns | |
| DOTCLK | T _{CYCD} | DOTCLK Cycle Time | 28 | - | ns | |
| | Trghr, Trghf | DOTCLK Rise/Fall time | - | 15 | ns | |
| DB | T _{PDS} | PD Data Setup Time | 5 | - | ns | |
| | T _{PDH} | PD Data Hold Time | 5 | - | ns | |

7. Optical Characteristics:

| Itom | | Chl | Carditians | Spe | cificat | ions | II | Nete |
|---------------|-------|-------|----------------------------|-----|---------|------|------|---------|
| Item | Item | | Symbol Conditions | | Тур | Max | Unit | Note |
| Transmit | tance | T(%) | - | - | 4.14 | - | - | - |
| Contrast] | Ratio | CR | θ =0° | | 900 | - | | (1) (2) |
| Response time | | TR+TF | Normal Viewing Angle | - | 35 | 45 | ms | (1) (3) |
| NTSO | NTSC | | - | - | 70 | - | % | Note 1 |
| | | θx+ | | - | 80 | - | | |
| Viewing | Hor. | θx- | | - | 80 | - | | (4) |
| Angle | Ver. | θу+ | CR≧10 | - | 80 | - | deg. | (1) |
| | | Өу- | | - | 80 | - | | |

Measuring Condition

- 1. Measuring surrounding: dark room
- 2. Ambient temperature: $25\pm2^{\circ}C$
- 3. 30 min. Warm-up time.

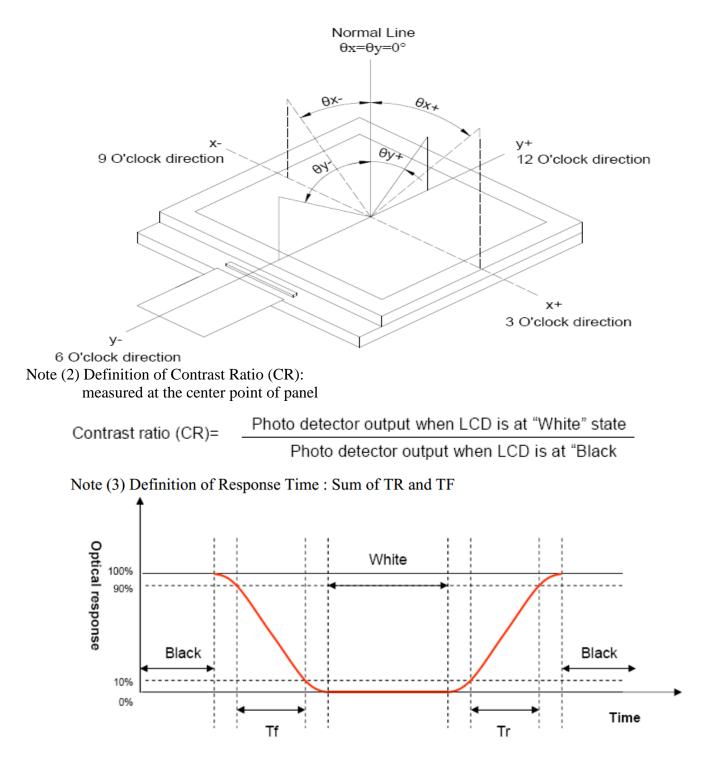
Color of CIE Coordinate:

| (T_0-2) | 5°C) | |
|-----------|------------|--|
| (1 a-2 | $J \cup J$ | |

| | | | | | (| 23(0) |
|-----------------------------|------------|---|-------------------------------------------------|-------|-------|-------|
| Item | Item | | Condition | Min. | Тур. | Max. |
| | Red | х | | 0.580 | 0.630 | 0.680 |
| | Red | у | | 0.293 | 0.343 | 0.393 |
| | Green | x | | 0.271 | 0.321 | 0.371 |
| Chromaticity Coordinates | | у | $\theta = \varphi = 0^{\circ}$ LED Backlight | 0.559 | 0.609 | 0.659 |
| (Transmissive) | Blue | x | | 0.092 | 0.142 | 0.192 |
| (manshinssive) | | у | | 0.050 | 0.100 | 0.150 |
| | TTT | x | | 0.246 | 0.296 | 0.346 |
| | White | у | | 0.193 | 0.243 | 0.293 |



Note (1) Definition of Viewing Angle:





8. Interface Pin Assignment:

8-1 TFT Pin Description:

| No. | Symbol | | | | F | unction | Remark | | |
|-----|--------|--------------------|---------------------|--------------|---------|--------------------------------------------|--------|--|--|
| 1 | LED K | LED ca | ED cathode | | | | | | |
| 2 | LED A | LED a | | | | | | | |
| 3 | NC | Not co | nnect. | | | | | | |
| 4 | NC | Not co | | | | | | | |
| 5 | NC | Not co | nnect. | | | | | | |
| 6 | NC | Not co | nnect. | | | | | | |
| 7 | VDD | Power | Supply | for an | alog Vo | oltage | | | |
| 8 | VDDI | | Supply | | | | | | |
| 9 | IM3 | IM3 | IM2 | IM1 | IM0 | MPU Interface Mode |] | | |
| | IM2 | 0 | 0 | 0 | 1 | RGB+8b SPI (fall) | | | |
| 10 | | 0 | 0 | 1 | 0 | RGB+9b SPI (fall) | | | |
| 44 | IM1 | 0 | 0 | 1 | 1 | RGB+16b SPI (rise) | | | |
| 11 | | 1 | 0 | 0 | 1 | RGB+8b SPI (rise) | 1 | | |
| 12 | IM0 | 1 | 0 | 1 | 0 | RGB+9b SPI (rise) | | | |
| 12 | | 1 | 0 | 1 | 1 | RGB+16b SPI (fall) | | | |
| 13 | SDO | Serial | data o | utput p | oin use | ed the for SPI interface | | | |
| 14 | SDA | | data inp nput da | | | rectional pin for SPI interface | | | |
| 15 | DCX | signal f Low: C | | mand o Id | | The SPI interface (DCX): The meter select. | | | |
| 16 | SCL | Serial of Serial i | nput clo | put for | SPI int | erface. | | | |
| 17 | NC | Not co | nnect | | | | | | |
| 18 | CSX | Low: t | | is se | lected | and accessible cted and not accessible. | | | |
| 19 | RESX | Reset | pin | | | | | | |
| 20 | DB23 | Data b | us | | | | | | |
| 21 | DB22 | Data b | us | | | | | | |
| 22 | DB21 | Data b | us | | | | | | |
| 23 | DB20 | Data b | | | | | | | |
| 24 | DB19 | Data b | | | | | | | |
| 25 | DB18 | Data b | us | | | | | | |
| 26 | DB17 | Data b | | | | | | | |
| 27 | DB16 | Data b | us | | | | | | |
| 28 | DB15 | Data b | us | | | | | | |
| 29 | DB14 | Data b | us | | | | | | |
| 30 | DB13 | Data b | us | | | | | | |
| 31 | DB12 | Data b | us | | | | | | |



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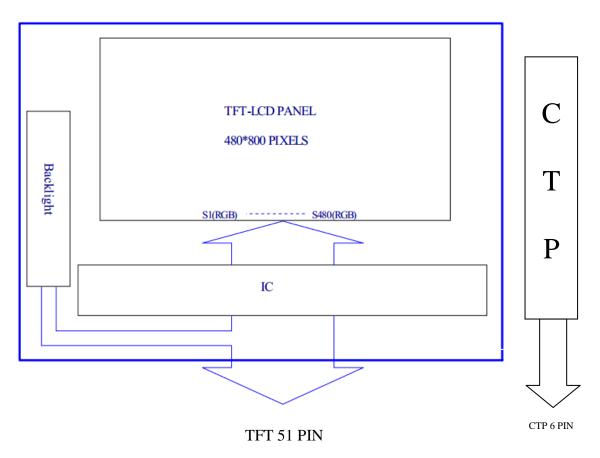
| No. | Symbol | Function | Remark |
|-----------|---------|---------------------------------------------------|--------|
| 32 | DB11 | Data bus | |
| 33 | DB10 | Data bus | |
| 34 | DB9 | Data bus | |
| 35 | DB8 | Data bus | |
| 36 | DB7 | Data bus | |
| 37 | DB6 | Data bus | |
| 38 | DB5 | Data bus | |
| 39 | DB4 | Data bus | |
| 40 | DB3 | Data bus | |
| 41 | DB2 | Data bus | |
| 42 | DB1 | Data bus | |
| 43 | DB0 | Data bus | |
| 44 | DE | Data enable signal in RGB interface. | |
| 45 | GND | Ground | |
| 46 | PCLK | RGB clock | |
| 47 | GND | Ground | |
| 48 | HS | Horizontal synchronizing signal in RGB interface. | |
| 49 | VS | Vertical synchronizing signal in RGB interface. | |
| 50 | TE | Tearing effect pin | |
| 51 | LED_PWM | Backlight control | |

8-2:Pin Description:

| 1 | RESET | Ι | Chip Enable |
|---|-------|-----|---------------------------------------------------|
| 2 | SDA | I/O | I ² C Serial Data |
| 3 | SCL | I/O | I ² C Serial Clock |
| 4 | INT | I/O | Interrupt signal/ Supports output open drain type |
| 5 | GND | Р | Ground |
| 6 | VDD | Р | Power Voltage for digital circuit |



9. Block Diagram:





10. Backlight:

- 1. Standard Lamp Styles (Edge Lighting Type): The LED chips are distributed over the edge light area of the illumination unit, which gives the less power consumption:
- 2. The Main Advantages of the LED Backlight are as following:
 - 2.1 The brightness of the backlight can simply be adjusted. By a resistor or a potentiometer.

| 3. Data About LED Backlight: (Ta=25°C) | | | | | | | |
|----------------------------------------|-------|-------|------|--------|-------------------|----------------|------|
| PARAMETER | Sym. | Min. | Тур. | Max. | Unit | Test Condition | Note |
| Supply Current | Ι | - | 20 | - | mA | V=26.4V | |
| Supply Voltage | V | 22.4 | 26.4 | 27.2 V | | | |
| Luminous Intensity for LCM | IV | - | 238 | - | cd/m ² | If=20mA | 2 |
| Uniformity for LCM | - | 80 | - | - | % | II=20IIIA | 3 |
| Life Time | - | 20000 | - | - | Hr. | | 4 |
| Color | White | | | | | | |

NOTE:

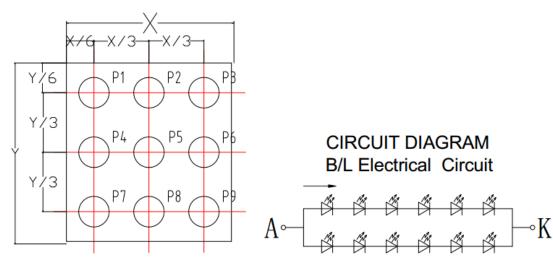
1. Backlight Only

- 2. Average Luminous Intensity of P1-P9
- 3. Uniformity = Min/Max * 100%

4. LED life time defined as follows: The final brightness is at 50% of original brightness

Measured Method: (X*Y: Light Area)

Internal Circuit Diagram



(Effective spatial Distribution) Using aperture of 1°, distance 50cm.



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11. Standard Specification for Reliability: 11–1. Standard Specifications for Reliability of LCD Module

| No | Item | Description |
|----|-----------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 01 | High temperature operation | The sample should be allowed to stand at 70° C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours. |
| 02 | Low temperature operation | The sample should be allowed to stand at -20° C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours. |
| 03 | High temperature storage | The sample should be allowed to stand at 80° C for 240 hours under no-load condition, and then returning it to normal temperature condition and allowing it stand for 2 hours. |
| 04 | Low temperature storage | The sample should be allowed to stand at -30° C for 240 hours under no-load condition, then returning it to normal temperature condition, and allowing it stand for 2 hours. |
| 05 | Moisture storage | The sample should be allowed to stand at 60° C, 90%RH MAX for 240 hours under no-load condition, then taking it out and drying it at normal temperature for 2 hours. |
| 06 | Thermal shock storage | The sample should be allowed to stand the following 10 cycles : -30°C for 30 minutes \rightarrow normal temperature for 5 minutes \rightarrow +60°C for 30 minutes \rightarrow normal temperature for 5 minutes, as one cycle. |
| 07 | Packing vibration | Frequency range : 10Hz ~ 55Hz Amplitude of vibration : 1.5mm Sweep time: 12 min X, Y, Z 2 hours for each direction. |
| 08 | Packing drop test | According toISTA 1A 2001. |

*Sample size for each test item is 3~5pcs



11 - 2. Testing Conditions and Inspection Criteria

For the final test the testing sample must be stored at room temperature for 24 hours, after the tests listed in Table 11-2, Standard specifications for Reliability have been executed in order to ensure stability.

| No | Item | Test Model | In section Criteria |
|----|------------------------|------------------------|--------------------------------------------------------------------------------------------------------------------|
| 01 | Current Consumption | Refer To Specification | The current consumption should conform to the product specification. |
| 02 | Contrast | Refer To Specification | After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests. |
| 03 | Appearance | Visual inspection | Defect free. |

11-3. MTBF

| MTBF | Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature $(25\pm5^{\circ}C)$, normal humidity $(50\pm10\%$ RH), and in area not exposed to direct sun light. |
|------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
|------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|



12. Specification of Quality Assurance:

12-1. Purpose

This standard for Quality Assurance should affirm the quality of LCD module products to supply to purchaser by YEEBO CORPORATION (Supplier).

12-2. Standard for Quality Test

a. Inspection:

Before delivering, the supplier should take the following tests, and affirm the quality of product.

b. Electro-Optical Characteristics:

According to the individual specification to test the product.

- c. Test of Appearance Characteristics:
 - According to the individual specification to test the product.
- d. Test of Reliability Characteristics:

According to the definition of reliability on the specification for testing products.

- e. Delivery Test:
 - Before delivering, the supplier should take the delivery test.
 - (i) Test method: According to ISO2859-1. General Inspection Level II take a single time.
 - (ii) The defects classify of AQL as following:

Major defect: AQL = 0.65%

- Minor defect: AQL = 2.5%
- Total defects: AQL = 2.5%
- 12-3. Non- conforming Analysis & Deal With Manners
 - a. Non- conforming Analysis:
 - (i) Purchaser should supply the detail data of non- conforming sample and the non-conforming.
 - (ii) After accepting the detail data from purchaser, the analysis of non- conforming should be finished in two weeks.
 - (iii) If supplier can not finish analysis on time, must announce purchaser before 3 days.
 - b. Disposition of non- conforming:
 - (i) If find any product defect of supplier during assembly time, supplier must change the good product for every defect after recognition.
 - (ii) Both supplier and customer should analyze the reason and discuss the disposition of non- conforming when the reason of nonconforming is not sure.

12-4. Agreement items

Both sides should discuss together when the following problems happen.

- a. There is any problem of standard of quality assurance, and both sides should think that must be modified.
- b. There is any argument item which does not record in the standard of quality assurance.
- c. Any other special problem.

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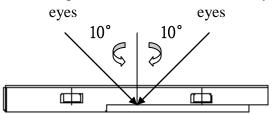
- 12-5. Standard of The Product Appearance Test
 - a. Manner of appearance test:

(i) The test must be under 20W $\times 2$ or 40W fluorescent light, and the distance of view must be at 30 \pm 5 cm.

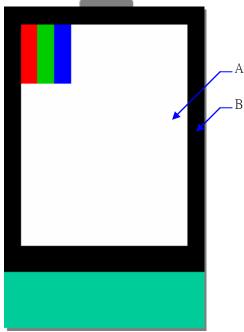
(ii) When test the model of transmissive product must add the reflective plate.

(iii)The test direction is base on around 10° of vertical line.

(iiii)Temperature: 25±5°C Humidity: 60±10%RH



(iv) Definition of area:



- A. Area: Viewing area.
- B. Area: Out of viewing area.

(Outside viewing area)

- b. Basic principle:
- (i) It will accord to the AQL when the standard can not be described.
- (ii) The sample of the lowest acceptable quality level must be discussed by both supplier and customer when any dispute happened.
- (iii) Must add new item on time when it is necessary.
- c. Standard of inspection: (Unit: mm)



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12-6. Inspection specification Defect out of viewing area can be neglected.

| NO | Item | Criterion | | | | AQL |
|----|-----------------------------------------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------------------------------------------------------|---------------------------------------------------------------------------------------------------------------|-------------------------------------------------------------------------------------------------------------------------------|------|
| 01 | Electrical Testing | 1.1 Open 1.2 Short 1.3 T/P failure 1.4 Missing vertical, 1.5 Missing character 1.6 Display malfunct 1.7 No function or no 1.8 Current consumption 1.9 LCD viewing ang 1.10 Mixed product to 1.11 Flicker | r, dot or icon. ion. o display. tion exceeds j gle defect. | - | | 0.65 |
| 02 | Black or White spots or Bright spots or Color spots on LCD (Display only) | 2.1 White and black of Five spots. 2.2 Densely spaced: N D = (X+Y)/2 $X \leftarrow Y$ Y | No more than | | | 2.5 |
| 03 | LCD and Touch Panel black spots, white spots, contamination (non – display) | 3.2 Line type: (As fol | nsely spaced: | Size(mm) D≤0. 15 0. 15 <d≤0. 25<br="">0. 25<d≤0. 35<br="">D>0. 35 No more than two</d≤0.></d≤0.> | Acceptable Q'ty Accept no dense 3 2 NG o spots within 3mm. Acceptable Q'ty Accept no dense 2 NG | 2.5 |



| NO | Item | Criterion | AQL |
|----|----------------------|-------------------------------------------------------------------------------------------------------------|-----|
| 04 | Polarizer bubbles | If bubbles are visible, judge using black spot specifications, not easy to find, must check in | - |
| 05 | Scratches | Follow NO.3 -2 Line Type. | 2.5 |
| 06 | Chipped glass | Symbols: x: Chip length y: Chip width t: Glass thickness | 2.5 |



| NO | Item | Criterion A | | | |
|----|-------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----|--|--|
| | | Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 7.2 Protrusion over terminal: 7.2.1 Chip on electrode pad: | | | |
| | | y: Chip width x: Chip length z: Chip thickness | | | |
| | | $y \leq 0.5 mm$ $x \leq 1/8a$ $0 < z \leq t$ | | | |
| 07 | Glass crack | 7.2.2 Non-conductive portion: y z z y z z x z z x z | 2.5 | | |
| | | y: Chip width x: Chip length z: Chip thickness | | | |
| | | $y \leq L \qquad x \leq 1/8a \qquad 0 < z \leq t$ | | | |
| | | ○ If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. ○ If the product will be heat sealed by the customer, the alignment mark must mot be damaged. 7.2.3 Substrate protuberance and internal crack Y: width x: length y: width x: length | | | |



| NO | Item | Criterion | AQL |
|----|-----------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------------------------|
| 08 | Cracked glass | The LCD with extensive crack is not acceptable. | 2.5 |
| 09 | Backlight elements | 9.1 Illumination source flickers when lit. 9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 9.3 Backlight doesn't light or color is wrong. | 2.5 2.5 0.65 |
| 10 | Bezel | Bezel must comply with product specifications. | 2.5 |
| 11 | РСВ、СОВ | 11.1 COB seal may not have pinholes larger than 0.2mm or contamination. 11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram. 11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 11.6 The jumper on the PCB should conform to the product characteristic chart. | 2.5 2.5 2.5 2.5 0.65 0.65 |
| 12 | FPC | 12.1 FPC terminal damage $\leq 1/2$ FPC terminal width and can not affect the function, we judge accept. 12.2 FPC alignment hole damage $\leq 1/2$ alignment area and can not affect the function, we judge accept. | 2.5 2.5 |
| 13 | Soldering | 13.1 No cold solder joints, missing solder connections, oxidation or icicle.13.2 No short circuits in components on PCB or FPC. | 2.5 0.65 |



| NO | Item | Criterion | | | | AQL |
|----------|-----------------------------------------|------------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------|-----------------------------------------------|--|------------|
| NO 14 | Item Touch Panel Chipped glass | z: Chip thickness Z≦t ⊙ Unit: mm | y: Chip width z: t: Touch Panel Total t gth hip: surface and crack betwo y: Chip width ≤ 1/2 k and not over viewing area | een panels: x: Chip length $x \le 1/8a$ | | AQL 2.5 |
| | | z: Chip thickness | y: Chip width $\leq 1/2$ k and not over | x: Chip length | | |
| | | z≦t | viewing area | x≤1/8a | | |
| | | ⊙ Unit: mm⊙ If there are 2 or m | nore chips, x is the total l | length of each chip | | |



| NO | Item | Criterion | AQL | | |
|----|-----------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------------|--|--|
| 15 | Touch Panel(Fish eye) | SIZE(mm)Acceptable Q'ty $D \leq 1.0$ Accept no dense $1.0 < D$ 0 | 2.5 | | |
| 16 | Touch Panel Newton ring | Newton ring dimension $\leq 1/2$ touch panel area and not affect font and ine distortion ($\leq 2.5\%$), it is acceptable. | | | |
| 17 | Touch Panel Linearity | Less than 2.5% is acceptable. | | | |
| 18 | LCD Ripple | Touch the touch panel, can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g | 2.5 | | |
| 19 | General appearance | 19.1 Pin type must match type in specification sheet. 19.2 LCD pin loose or missing pins. 19.3 Product packaging must the same as specified on packaging specification sheet. 19.4 Product dimension and structure must conform to product specification sheet. | 0.65 0.65 0.65 0.65 | | |



<u>13. Handling Precaution:</u>

13-1 Handling of LCM

- Don't give external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance. Must not lick and swallow. when the liquid is attach to your hand, skin, cloth etc. Wash it out thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should be grounded whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads,the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.

13-2 Storage

- Store in an ambient temperature of 25±10°C, and in a relative humidity of 50±10% RH , and must be used within six months after delivery from our factory. Don't expose to sunlight or fluorescent light.
- Storage in a clean environment, free from dust, active gas, and solvent.
- Store in anti-static electricity container.
- Store without any physical load.
- Appearance,3months;Function,1year;within the validity, failed CTP can be replaced 1 to 1

13-3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: No higher than $280\pm10^{\circ}$ C and less than 3 sec during Hand soldering.
- Rewiring: no more than 2 times.

14. Guarantee:

Our products meet requirements of the environment.

YEEBO ROHS requirement is based on European Union Directive 2011/65/EU (ROHS) Requirements and Update.